

**CLEAN COPY OF PENDING CLAIMS**

20. An assembly, comprising:

a film including a plurality of substrate units with said plurality of substrate units being adapted to electrically interface with a plurality of dies, each one of said substrate units including a substantially central cavity adapted to receive wires from a corresponding die which connect to a first surface of said film, said dies being attachable to a second surface of said film with said second surface being opposed to said first surface; and

a carrier in mechanical communication with said first surface of said film for providing enhanced rigidity to said film by being sized and configured to add material at selected regions of said film.

DI 21. The assembly of Claim 20, wherein said plurality of substrate units are grouped into substrate sets.

22. The assembly of Claim 21, wherein said substrate sets comprises three substrate units.

23. The assembly of Claim 22, wherein said carrier further comprises a plurality of cross bars and wherein each cross bar is located near a substrate set.

24. The assembly of Claim 20, wherein said plurality of dies comprise lead-over-chips (LOC).

26. The assembly of Claim 20, wherein said film comprises polyimide.

29. The assembly of Claim 20, wherein each one of said plurality of substrate units includes a pair of adhesive tabs.

30. The assembly of Claim 20, wherein each one of said plurality of substrate units includes a plurality of alignment holes.